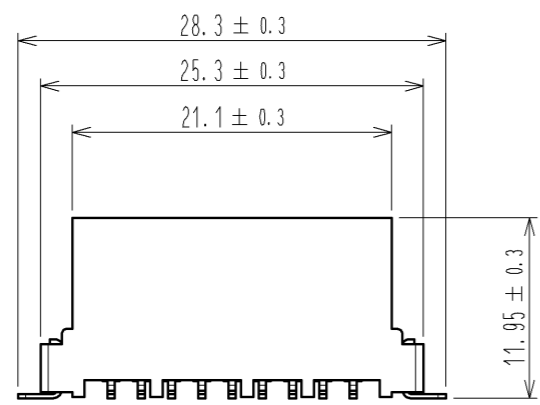
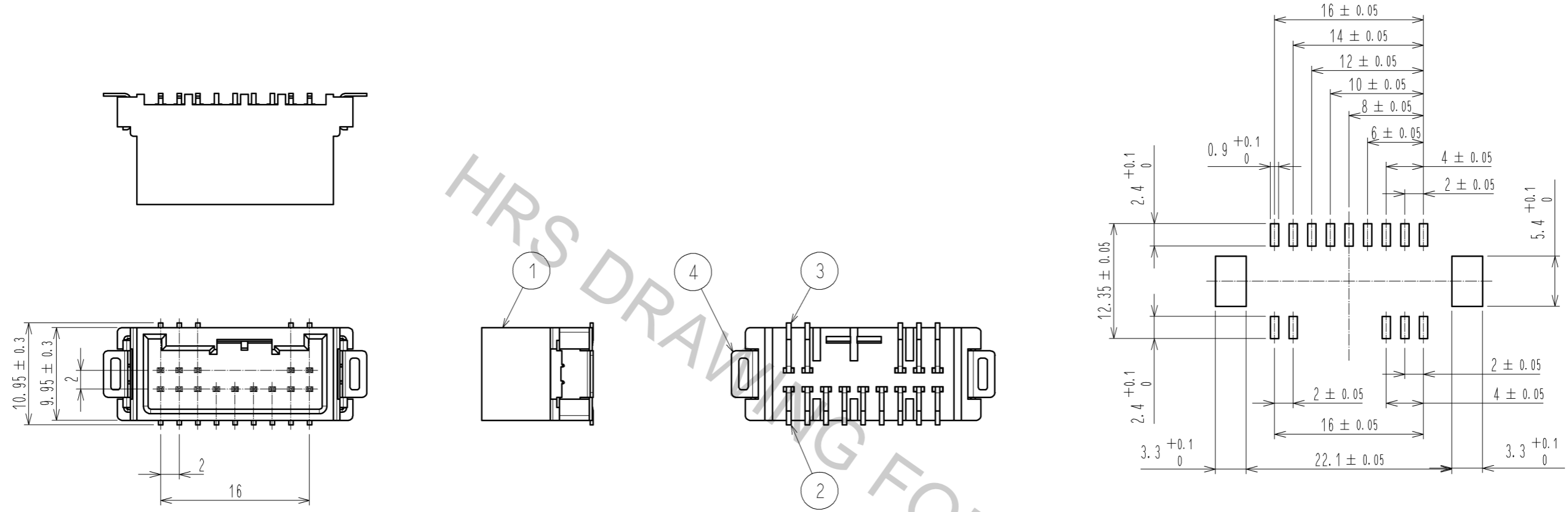
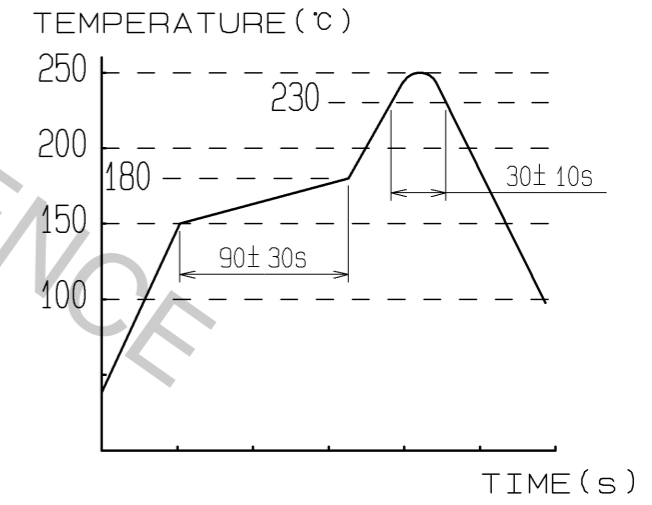


ELV. RoHS COMPLIANT



NOTE1. RECOMMENDED TEMPERATURE PROFILE FOR REFLOW (REFER RIGHT FIG.).

- REFLOW HEATING: FAR-INFLARED, IN THE AIR OR NITROGEN
- REFLOW No. : MAX 2 TIMES
- PEAK TEMPERATURE : 250°C
- ABOVE 230°C : 20~40s
- PREHEAT : 150~180°C (60~120s)
- 2. SOLDERING TEMPERATURE : 280~300°C (MAX 2s)
- 3. COPLANARITY OF LEADS SHALL BE UNDER 0.1mm.
- 4. RECOMMENDED THICKNESS FOR PC BOARD IS 1.6mm.
- 5. RECOMMENDED THICKNESS FOR SOLDER PASTE IS 0.15mm.
- 6. TIN PLATING, PARTIAL GOLD PLATING (CONTACT AREA)



2	BRASS	NOTE 6	4	BRASS	TIN PLATING
1	PPS	BLACK	3	BRASS	NOTE 6
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
UNITS mm		SCALE 2 : 1	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : AR. SHIRAI	11.12.22	DRAWING NO.	EDC3-168823-01
		CHECKED : AR. SHIRAI	11.12.22	PART NO.	GT8EH-14DP-2V(C01)
		DESIGNED : NA. HARUBAYASHI	11.12.22	CODE NO.	CL758-0225-5-01
		DRAWN : NA. HARUBAYASHI	11.12.22		1/1